

# High Current, Low-Profile Power Inductors

## FLAT-PAC™ FP1105 Series



### **Description**

- 125°C maximum total temperature operation
- 11.0 x 8.0 x 4.90mm surface mount package
- · Ferrite core material
- · High current carrying capacity
- Low core losses
- Controlled DCR tolerance for sensing circuits
- Inductance range from 101nH to 226nH
- Current range from 39 to 81Amps
- Frequency range up to 2MHz
- RoHS compliant

## **Applications**

- Multi-phase regulators
- Voltage Regulator Module (VRM)
- · Portable electronics
- · Servers and workstations
- Data networking and storage systems
- Notebook and desktop computers
- · Graphics cards and battery power systems
- DCR sensing

#### **Environmental Data**

- Storage temperature range: -40°C to +125°C
- Operating temperature range: -40°C to +125°C (Range is application specific)
- Solder reflow temperature: J-STD-020D compliant

#### **Packaging**

• Supplied in tape and reel packaging, 900 parts per reel, 13" dia. reel

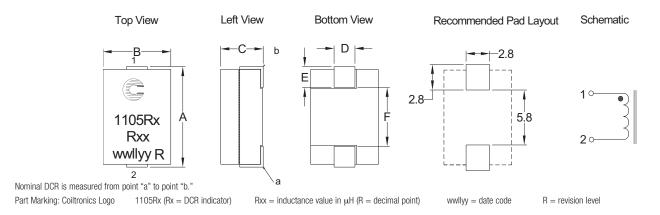
	Product Specifications						
Part Number	OCL1 ± 10% (nH)	FLL <sup>2</sup> Min. (nH)	I <sub>rms</sub> <sup>3</sup> (Amps)	I <sub>sat</sub> 1 <sup>4</sup> @ 25°C (Amps)	I <sub>sat</sub> 2 <sup>5</sup> @ 125°C (Amps)	DCR (mΩ) @ 20°C	K-factor <sup>6</sup>
FP1105R1-R10-R	100	72		81	63		467
FP1105R1-R12-R	120	86		66	50		467
FP1105R1-R15-R	150	109	46	54	42	$0.35 \pm 8.6\%$	467
FP1105R1-R20-R	192	138		42	34		467
FP1105R1-R22-R	226	163		39	28		467

- 1 Open Circuit Inductance (OCL) Test Parameters: 100kHz, 0.10V<sub>rms</sub>, 0.0Adc
- 2 Full Load Inductance (FLL) Test Parameters: 100kHz, 0.1V<sub>rms</sub>, I<sub>sat</sub>1
- 3  $\,$  I $_{rms}$ : DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB pad layout, trace thickness and width, air-flow and proximity of other heat generating components will affect the temperature rise. It is recommended the part temperature not exceed 125°C under worst case operating conditions verified in the end application.
- 4 I<sub>sat</sub>1: Peak current for approximately 20% rolloff at +25°C.
- 5 I<sub>sat</sub>2: Peak current for approximately 20% rolloff at +125°C.
- 6 K-factor: Used to determine  $B_{p-p}$  for core loss (see graph).  $B_{p-p} = K \star L \star \Delta I \star 10^{-3}$ ,  $B_{p-p}$ : (Gauss), K: (K-factor from table), L: (inductance in nH), ΔI (peak-to-peak ripple current in amps).
- 7 Part Number Definition: FP1105Rx-Rxx-R
  - FP1105 = Product code and size
- · Rx is the DCR indicator
- Rxx= Inductance value in μH, R = decimal point
   "-R" suffix = RoHS compliant

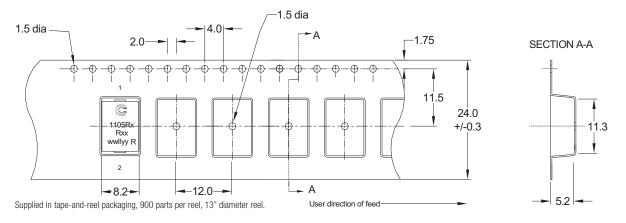
RoHS 2002/95/EC

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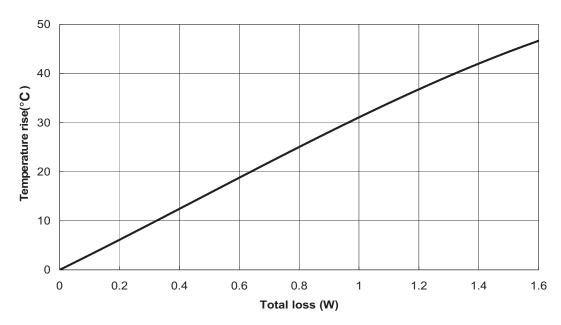
**Dimensions - mm** A = 11.0 Max. B = 8.0 Max. C = 4.9 Max. D =  $2.4 \pm 0.2$  E =  $2.3 \pm 0.3$  F = 6.2 Typ.



## Packaging Information - mm



## **Temperature Rise vs. Total Loss**

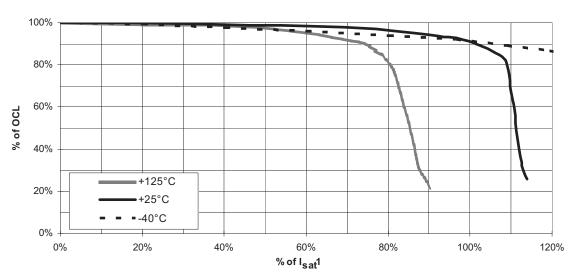


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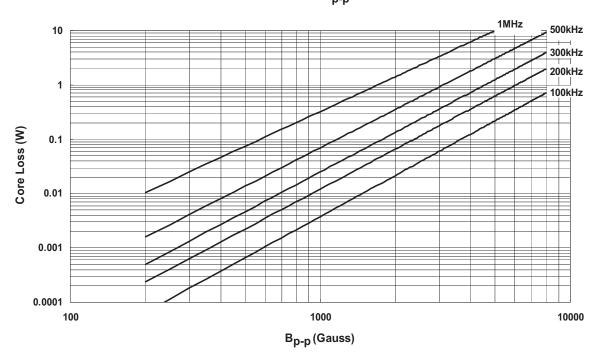
## **Inductance Characteristics**





## **Core Loss**

## Core Loss vs. B<sub>p-p</sub>



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#### Solder Reflow Profile

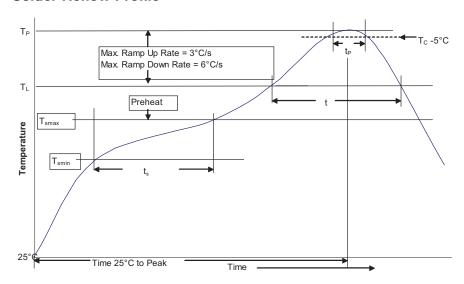


Table 1 - Standard SnPb Solder (T<sub>c</sub>)

	Volume	Volume
Package	mm³	$mm^3$
Thickness	<350	≥350
<2.5mm	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (Tc)

Package Thickness	Volume mm³ <350	Volume mm <sup>3</sup> 350 - 2000	Volume mm³ >2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

#### Reference JDEC J-STD-020D

Profile Feature		Standard SnPb Solder	Lead (Pb) Free Solder	
Preheat and Soak	<ul> <li>Temperature min. (T<sub>smin</sub>)</li> </ul>	100°C	150°C	
	Temperature max. (T <sub>smax</sub> )	150°C	200°C	
	• Time (T <sub>smin</sub> to T <sub>smax</sub> ) (t <sub>s</sub> )	60-120 Seconds	60-120 Seconds	
Average ramp up rat	te T <sub>smax</sub> to T <sub>p</sub>	3°C/ Second Max.	3°C/ Second Max.	
Liquidous temperature (TL)		183°C	217°C	
Time at liquidous (t <sub>L</sub> )		60-150 Seconds	60-150 Seconds	
Peak package body	temperature (T <sub>P</sub> )*	Table 1	Table 2	
Time (t <sub>p</sub> )** within 5	°C of the specified classification temperature (T <sub>C</sub> )	20 Seconds**	30 Seconds**	
Average ramp-down	rate (T <sub>p</sub> to T <sub>smax</sub> )	6°C/ Second Max.	6°C/ Second Max.	
Time 25°C to Peak Temperature		6 Minutes Max.	8 Minutes Max.	

 $<sup>^{\</sup>star}$  Tolerance for peak profile temperature (T<sub>p</sub>) is defined as a supplier minimum and a user maximum.

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 $<sup>^{\</sup>star\star}$  Tolerance for time at peak profile temperature (t<sub>p</sub>) is defined as a supplier minimum and a user maximum.